

Microminiature Connectors

Wire-to-Wire | Wire-to-Board

molex[®]

Features and Benefits

Pitch: 0.40 to 6.20mm

Current: 0.2 to 15.0A

Wire Size: 14 to 42 AWG

Circuits: 1 to 50

Positive and friction lock options



Description	Pitch	Current Rating	Wire Size	Configuration	Plating	Circuits	Locking	Key Features
TermiMate™	NA	3.0A	22 - 26	Right angle WTB Coplanar BTB	Tin	1	Positive	Space saving
Micro IDT Coaxial	0.40mm	0.2A	42 AWG	W-to-B Top entry Side entry	Gold	30, 40, 50	Friction	Shielded end-to-end
Pico-Clasp™	1.00mm	1.0A	28-32 AWG	W-to-B Single row Dual row Vertical Right angle	Single: Tin Dual: Gold	Single: 2-15 Dual: 10, 30, 40, 50	Positive	Positive latched, small, variation
Pico-Lock™	1.00	1.5A	28, 30	WTB in right angle	Gold	2, 4	Positive	Low profile
Pico-EZmate™	1.20mm	1.5A	28-30 AWG	W-to-B Right angle Single row	Gold	2-7	Friction	Z-axis mating, easy operation Low-profile
PicoBlade™	1.25mm	1.0A	26-32 AWG	W-to-B W-to-W Vertical Right angle Single row Thru-hole & SMT	Tin	2-15	Friction	Variation Availability
CLIK-Mate™	1.25mm	1.0A	26-28 AWG	W-to-B Vertical Right angle Single row	Tin	2-15	Positive	Positive interia lock, Stub-free mating interface
Duo-Clasp™	1.25mm	1.0A	26-28 AWG	W-to-B Vertical Right angle Dual row	Gold	20, 30, 40	Positive	Positive inner-lock
Micro-Lock™	1.25mm	1.5A	26-30 AWG	W-to-B W-to-W Vertical Right angle Single row Dual row	Tin	Single: 2-16 Dual: 16-40	Positive	Positive lock-variation
Pico-SPOX™	1.50mm	2.50A	24-30 AWG	W-to-B Vertical Right angle Single row	Tin	2-15	Friction	High-current
Pico-Lock™	1.50mm	3.0A	24-28 AWG	W-to-B Right angle Single row	Gold	4-12	Positive	Low-profile Positive side latch
CLIK-Mate™	1.50	2.0A	24 - 28	WTB, vertical & R/A, single & dual row	Tin	2 - 15 (single) 8 - 34 (dual)	Positive	Positive interia lock Stub-free mating interface

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Description	Pitch	Current	Wire Size	Configuration	Plating	Circuits	Locking	Key Features
CLIK-Mate™	2.00mm	3.0A	22-26 AWG	W-to-B Vertical Right angle Single row	Tin	4-15	Positive	Positive interia lock Stub-free mating interface
MicroClasp™	2.00mm	3.0A	22-28 AWG	W-to-B Vertical Right angle Single row Dual row	Tin	2-15 (single row) 8-40 (dual row)	Positive	Positive inner-lock
iGrid™	2.00mm	2.0A	22-28 AWG	W-to-B Vertical Right angle Dual row	Tin	10-40	Positive	Positive inner-lock
Sherlock™	2.00mm	2.0A	24-30 AWG	W-to-B Vertical Right angle Single row	Tin	2-15	Positive	Positive lock
MicroTPA™	2.00mm	2.5A	22-28 AWG	W-to-B W-to-W Vertical Single row	Tin	2-15	Positive	Positive interia lock Portable PCB header TPA
DuraClik™ TPA (wire side only)	2.00mm	3.0A	22, 24 AWG	W-to-B Single row Vertical Right angle	Tin	2-15	Positive	Positive inner-lock TPA
Mini-Lock™	2.50mm	0.03A	22-28 AWG	W-to-B W-to-W Single row Vertical Right angle	Tin	2-15	Positive	Positive lock, portable header
Mini-Latch™	2.50mm	3.0A	22-28 AWG	W-to-B WTW Single row Vertical Right angle	Tin	2-15	Friction	W-to-B W-to-W
Mini-SPOX™	2.50mm	3.0A	22-28 AWG	W-to-B Single row Vertical Right angle	Tin	2-15	Friction	
Flexi-Mate™	3.70mm	2.0A	26-28 AWG	Right angle W-to-B Coplanar B-to-B Single row terminator	Tin	2	Positive Friction	W-to-B B-to-B Loopback terminator
Lite-Trap™	4.00mm	9.0A	18-24 AWG	W-to-B Right angle Single row	Tin	1, 2	Poke-in	Toolless
Board-in	2.00mm, 2.50mm, 4.00mm, standalone	2.0-5.0A	18-30 AWG	W-to-B Vertical and right angle Single row	Tin	2-15	Permanent solder	Cost efficient
VersaBlade™	6.20mm	15.0A	14-26 AWG	W-to-W	Tin	1-9	Positive	Multi branched wiring TPA Panel mount Glow wire capable

Microminiature Connectors

Board-to-Board | FFC/FPC

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Features and Benefits

Board-to-Board

FFC/FPC

Pitch: 0.35 to 1.00mm

Pitch: 0.20 to 1.25mm

Speed: Up to 20 Gbps

Height: As low as 0.75mm

Stack Heights: 0.60 to 20.00mm

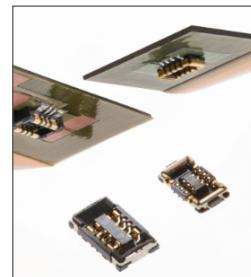
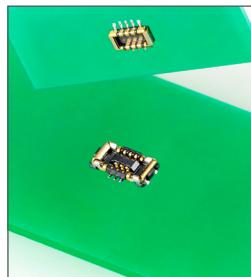
Circuits: 4 to 96-circuits

Circuits: 6 to 240

Various actuator options

Friction lock

Can combine signal and power



Description	Pitch	Stack Height	Configuration	Plating	Circuits	Locking	Speed	Key Features
SlimStack™	0.35-1.00mm	0.60-20.0mm	SMT B-to-B Flex-to-B	Gold	6-240	Friction*	3 -20 Gbps	Single or dual contact, narrow width, lower stack heights
0.80 Board-to-Board	0.80mm	4.50-4.70mm	SMT B-to-B Vertical Right angle	Tin	10-40	Friction	Up to 3 Gbps	Right angle option
SlimStack Armor™	0.35mm	0.60mm (0.70, 0.80 and 1.00mm coming soon, scaleable version)	SMT B-to-B Flex-to-B	Gold	6, 12, 16, 22, 24, 30, 34, 40, 48, 50	Friction	Up to 20 Gbps	Armor metal cover with integral power nail
SlimStack™ Board-to-Board	0.40mm	0.80mm	SMT B-to-B Flex-to-B	Gold	10-60	Friction	Up to 20 Gbps	Metal cover nail

FFC/FPC	0.20-1.25mm, and .075mm lowest height (LA75)		C-to-B	Gold, Tin, Tin-Bismuth, Tin-Silver-Bismuth	4-96	Friction, actuator and limited positive lock in 0.50mm	Up to 10 Gbps	Double contact for high electrical reliability
FFC/FPC FD19	0.50mm Height: 1.90mm		C-to-B	Gold	4-80	Friction	Up to 5 Gbps	Ears to help with alignment and retention

* Also offer higher retention force version on 0.40mm only

Microminiature Connectors

Memory Card Connectors

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Features and Benefits

Push/Push and Push/Pull offerings

SMT and through hole offerings

Available in 1 and 2-ports

Multiple standards available



Description	Pitch	Circuits	Termination Style	Ports
microSD*	1.09-2.54mm	8, 9	SMT Through hole	1, 2
microSD/SIM	1.10 -2.54mm	8	SMT	2
microSIM	1.10 -2.54mm	6, 7, 8	SMT	1, 2
SIM (2ff, 3ff, 4ff)	1.10-2.54mm	6, 7, 8	SMT	1, 2, 8
Chip SIM	2.54-7.32mm	6	SMT	1
CompactFlash	1.27mm	50	SMT	1
SD (Secure Digital)	2.50mm	9	SMT	1

*microSD is a trademark of the SD Card Association

www.molex.com/link/microconnectors.html